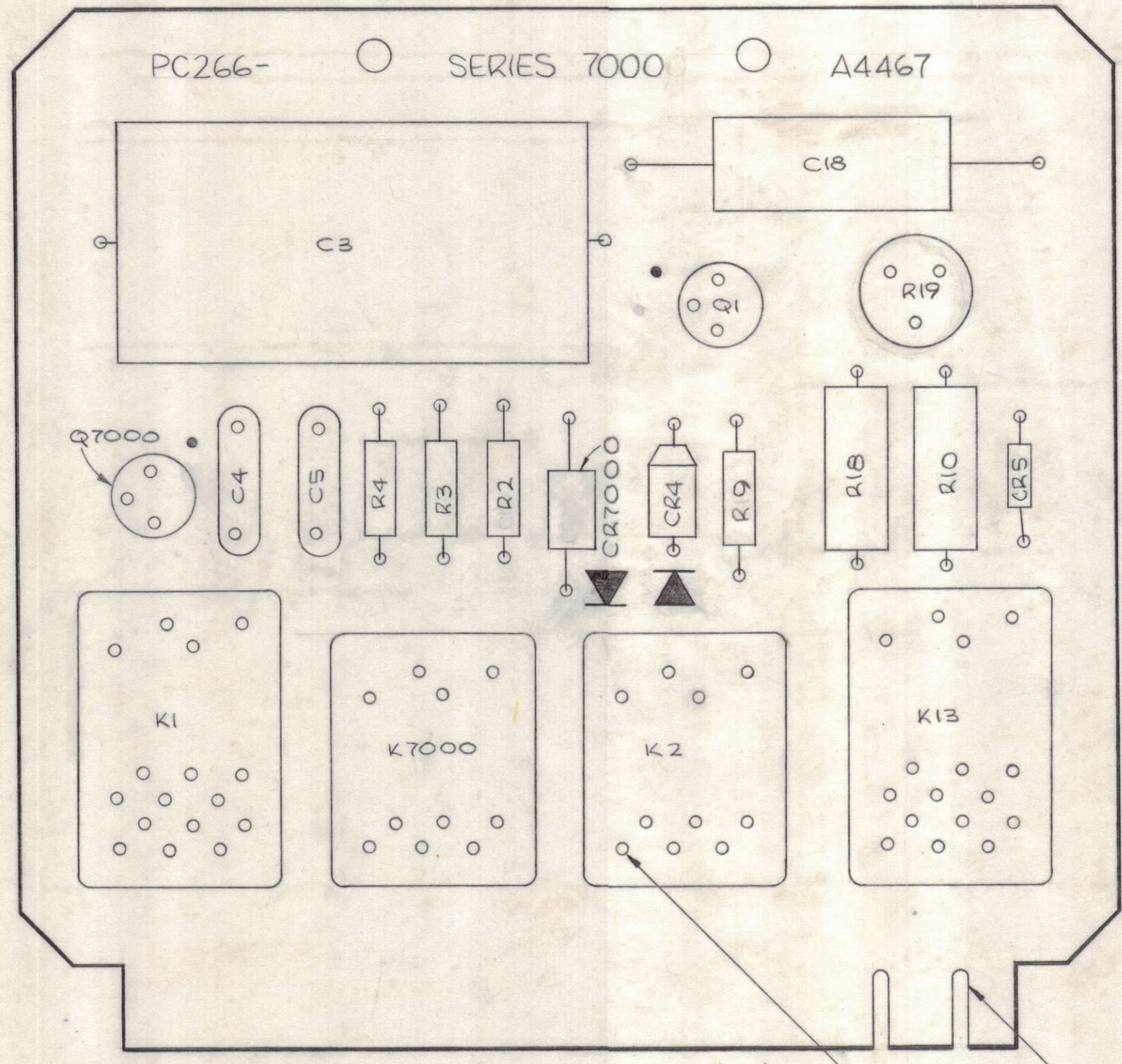


REVISIONS							
SYM	ZONE	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
X1		IT, Z1 WAS R19 ERROR	3-7-67				
Ø		ORIGINAL RELEASE FOR PRODUCTION	3-27-67		RME		



ASSEMBLY NOTES

- 1- TO MOUNT COMPONENTS INSERT LEADS THRU PLATED-THRU HOLES
- 2- APPLY HEAT & SOLDER TO LEAD & FOIL. — CAUTION: TOO MUCH HEAT WILL CAUSE FOIL TO SEPARATE FROM THE BOARD.
- 3- CLEAN AND INSPECT PER 5676. LEADS THRU PLATED-THRU HOLES.
- 4- FUNGUS PROOFING PER TMC SPEC 5113. — CAUTION: TO MOUNT
- 5- BOARD EDGES MUST BE CLEARED OF SOLDER APPROXIMATELY 3/16 FROM EDGES.

QTY REQ	ITEM	PART NO.	DESCRIPTION	SYMBOL
X	22	BS100	SOLDER, TIN ALLOY	
1	21	RC20GF2213	RES, FIXED COMP	R9
2	20	TS171-5	SOC, REL, W/RET	XK7000, XK2
2	19	TS171-4	SOC, REL, W/RET	XK1, XK13
1	18	RL156-10	REL, ARM -4PDT	K1
1	17	RL156-9	REL, ARM -DPDT	K2
1	16	RL156-2	REL, ARM -4PDT	K13
1	15	RL156-1	REL, ARM -DPDT	K7000
1	14	2N492	TRANSISTOR	Q1
1	13	2N697	TRANSISTOR	Q7000
1	12	IN3027B	SCOND, DEV, DIO	CR7000
1	11	IN2484	↓ ↓ ↓	CR4
1	10	IN270	SCOND, DEV, DIO	CR5
1	9	CE116-10VN	CAP, FIXED, ELECT	C3
2	8	CC100-33	↓ ↓ ↓	C4, C5
1	7	CE105-100-25	CAP, FIXED ELECT	C18
1	6	RV111U504A	RES, VAR COMP, PC	R19
1	5	RC20GF4743	RES, FIXED COMP	R4
1	4	RC20GF2233	↓ ↓ ↓	R2
1	3	RC20GF2223	↓ ↓ ↓	R3
2	2	RC32GF2213	RES, FIXED COMP	R10, R18
1	1	PC 266	PC BOARD	

HOLES SHOWN FOR COMPONENT MOUNTING, USED FOR REFERENCE ONLY.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON FRACTIONS DECIMALS ANGLES ±1/64 ±.005 ±1/2°

MATERIAL ————

FINISH ————

FINAL APPROVAL	DATE
MECH. DES.	DATE
ELECT. DES.	DATE
CHECKED	DATE
DRAWN	DATE
CONTRACT NO. 5401-451 5401-5401-	

F. BUDETTI BILL OF MATERIAL

THE TECHNICAL MATERIEL CORP.
MAMARONECK, NEW YORK

ASS'Y, PRINTED CIRCUIT BD
RELAY CKT (SWCA-3.K)

CODE	SIZE	DWG. NO.	ISSUE
82679	C	A4467	Ø
SCALE	SHEET		OF

1	SWCA-3K	12-3-66
QTY-UNIT	MODEL USED ON	DATE
MAXIMUM ALLOWABLE TOLERANCES HAVE BEEN DETERMINED AND ANY DEVIATIONS WILL BE CAUSE FOR REJECTION.		